EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6096	(single or whole or one) near10 (leadframe or lead-frame or lead adj frame) near10 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:07
L2	87	(single or whole or one) near10 (leadframe or lead-frame or lead adj frame) near10 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact) near10 (heat adj sink)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:09
L3	7	(single or whole) near10 (leadframe or lead-frame or lead adj frame) near10 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact) near10 (heat adj sink)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:10
L4	610	(leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (heat adj sink) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near7 (chip or die or sensor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:13
L5	294	(leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (heat adj sink) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near7 (chip or die or sensor) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:16

L6	54759	((leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (rout$3 or circuit$2 or connect$3 or interconnect$3 or contact) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near5 (heat adj sink) and (leadframe or lead-frame or lead adj frame or conductive near2 substrate) near7 (chip or die or sensor) or (leadframe or lead-frame or lead adj frame or conductive near2 substrate with heat adj sink with (monolithic or mono-lithic or mono adj lithic)))and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:18
L7	54754	(leadframe or lead-frame or lead adj frame or conductive near2 substrate with heat adj sink with (monolithic or mono-lithic or mono adj lithic) with routing adj circuit$2)and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:19
L8	0	((leadframe or lead-frame or lead adj frame or conductive near2 substrate) with heat adj sink with (monolithic or mono-lithic or mono adj lithic) with routing adj circuit$2) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:30
L9	0	((leadframe or lead-frame or lead adj frame or conductive near2 substrate) with heat adj sink with routing adj circuit$2) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:30
L10	3	((leadframe or lead-frame or lead adj frame or conductive near2 substrate) with routing adj circuit$2) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 12:32
L11	421	((etch$3) near8 (connect$3 or routing adj circuit$2) near5 (die or chip)) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:27

EAST Search History

L12	66	((etch$3) near8 (connect$3 or routing adj circuit$2) near5 (die or chip) and (heat or thermal) near5 conduct$3) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:29
L13	164	heat adj sink near5 (single or monolithic$4) near7 (conduct$3 or metal) and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:33
L14	44	heat adj sink near7 substrate near5 etch$3 and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:53
L15	0	heat adj sink near7 leadframe near5 etch$3 and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:53
L16	0	heat adj sink near7 lead-frame near5 etch$3 and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:53
L17	0	heat adj sink near7 lead adj frame near5 etch$3 and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:53
L18	1	heat adj sink near10 lead adj frame near10 etch$3 and @py<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:55

EAST Search History

L19	1	heat adj sink near10 lead adj frame near10 etch$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:55
L20	1	((thermal or heat) near3 conduct$3) near10 lead adj frame near10 etch$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:56
L21	371	((thermal or heat) near3 conduct$3) near10 lead adj frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:56
L22	249	((thermal or heat) near3 conduct$3) near5 lead adj frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:57
L23	0	((thermal or heat) near3 conduct$3) near5 lead adj frame with land	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:57
L24	44	((thermal or heat) near3 conduct$3) near5 lead adj frame with bond$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/15 13:57
S1	221	257/666,667,672,673,675,787.ccls. and (semiconductor with (encapsul$4 or mold$3) and land and lead adj frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 12:59

S2	0	"60594859".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 12:59
S3	6	("5969426" | "6215179" | "6247229" | "6278177" | "6294830" | "6309909").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 13:41
S4	8	("5285352" | "5355283" | "5371404" | "5394009" | "5450283" | "5461197" | "5554887" | "5619070").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 13:54
S5	237	"257".clas. and ((plurality near3 (ball or sphere or bump) with seal$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 15:17
S6	0	"9990083"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:35
S7	0	("9990083").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 16:35
S8	0	"9990083".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:35
S9	0	"09990083".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:37

S10	0	(method adj2 apparatus adj2 leadframe adj based adj grid adj array adj ic adj packaging).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:38
S11	1	(method adj2 apparatus adj2 lead-frame adj based adj grid adj array adj ic adj packaging).ti.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:51
S12	2	("20020168796").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:10
S13	2	"6670222".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:26
S14	0	("jp2004-71898").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:26
S15	0	("jp200471898").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:26
S16	0	jp200471898.pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:27

S17	0	"200471898".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:27
S18	0	("2004-71898.pn.").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 17:27
S19	0	jp2004-71898.pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 17:29
S20	2	("20020168796").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/01 18:54
S21	2	"5969426".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:56
S22	0	"257".clas. and (heat adj sink) and (passive adj device) and (thickness with chip adj attach$4 adj site)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:58
S23	0	"257".clas. and (thickness with chip adj attach$4 adj site)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 18:58

S24	86	"257".clas. and (thickness with chip adj attach$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:00
S25	1	"257".clas. and (distance with semiconductor near3 (routing adj circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:02
S26	1	distance with semiconductor near3 (routing adj circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 19:03
S27	2	"6185240".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 16:43
S28	2	"4365226".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 16:43